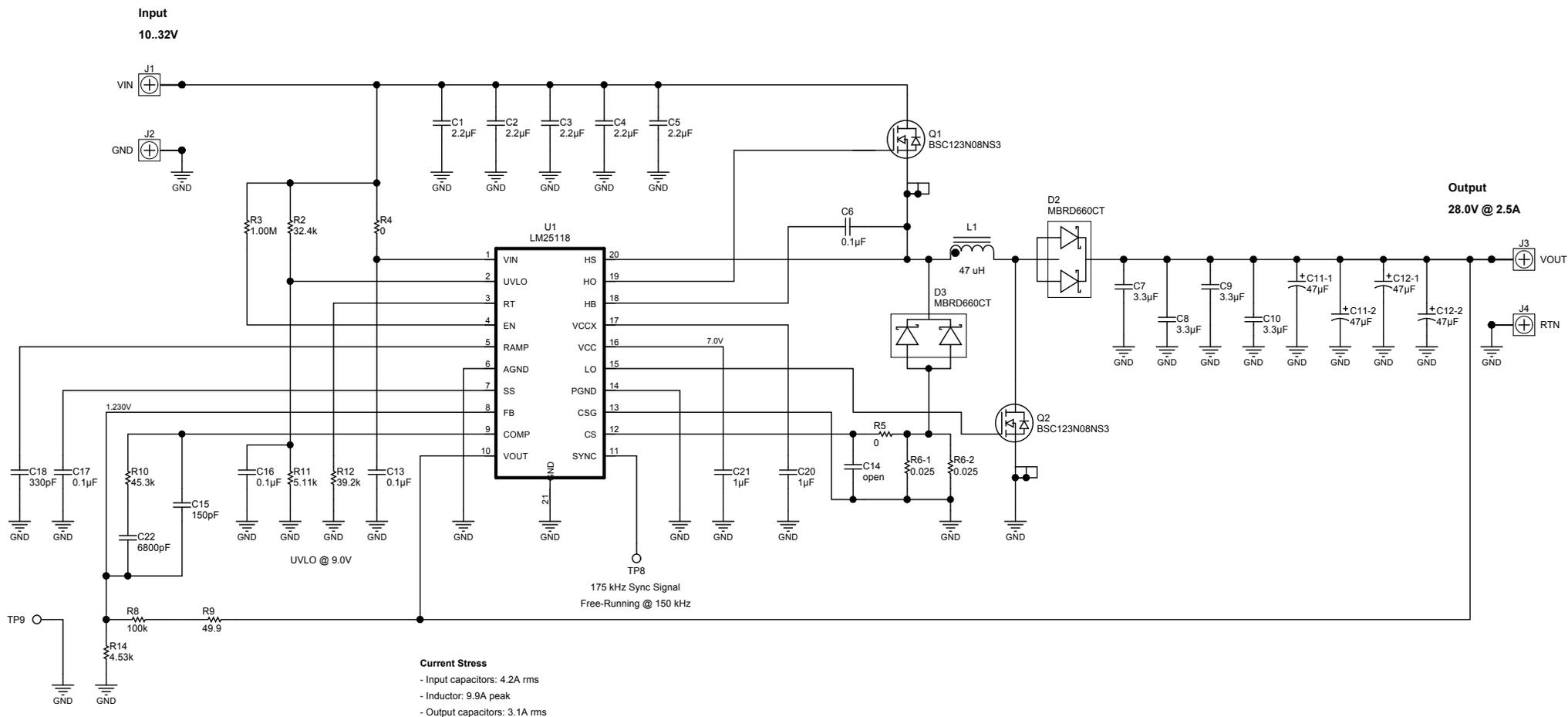


Revision History	
Revision	Notes
A	* First release, paper design
B	* Modified LM25118 EVM, tested



Notes
- Part Numbers fit for EVM "LM25118 Evaluation Board"

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Designed for: Public Release	Mod. Date: 4/19/2013
Project Title: Buck-Boost 10.32V -> 28V @ 2.5A	
Number: PMP8570	Rev: B
SVN Rev: Not in version control	Sheet Title:
Drawn By:	Assembly Variant: Variant name not interpreted Sheet: 1 of 1
Engineer: Matthias Ulmann	File: PMP8570RevB_SchDoc
	Contact: http://www.ti.com/support
	Size: A3



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